

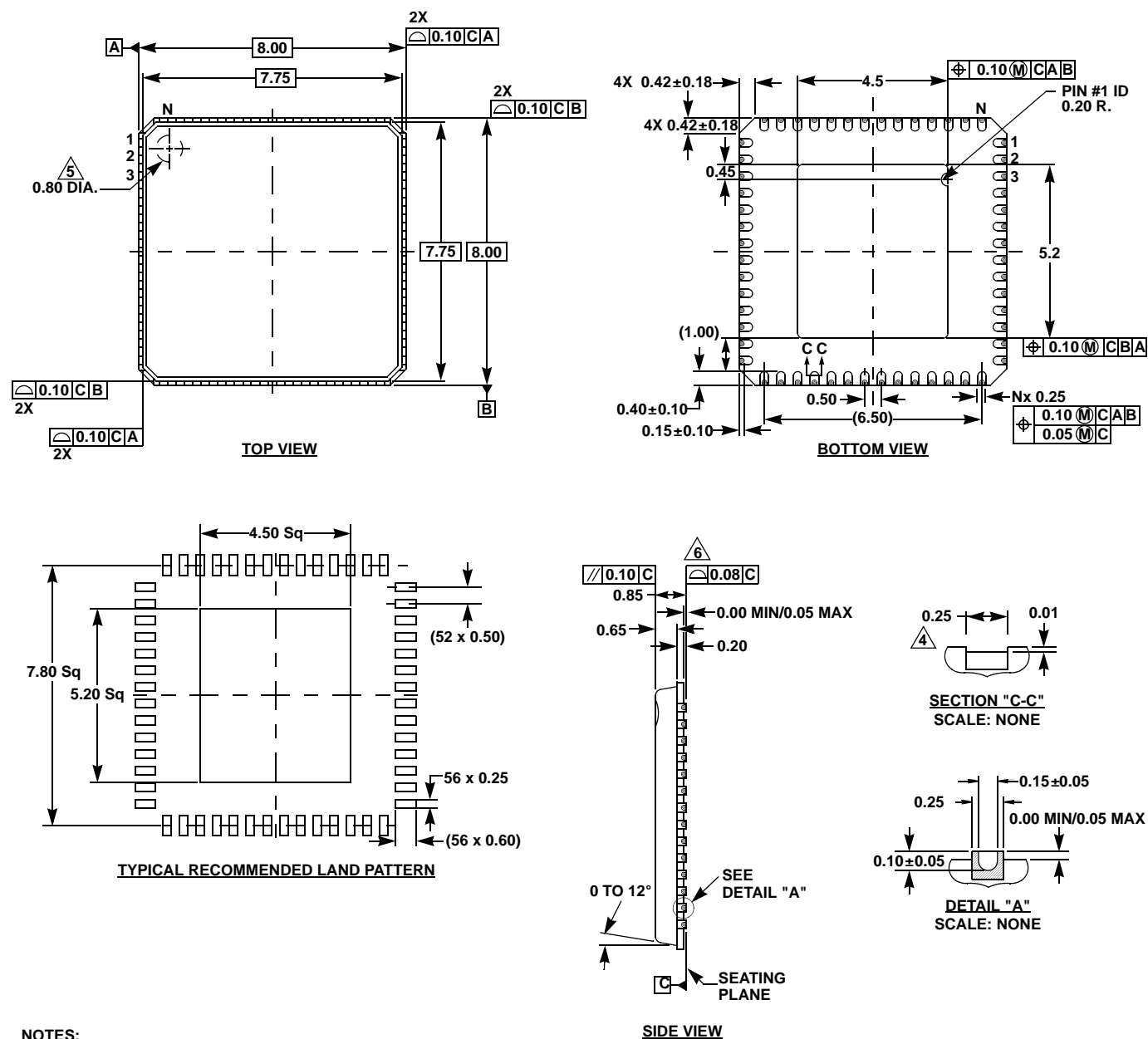
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### L56.8x8G

56 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN WITH WETABLE FLANK)

Rev 1, 2/14



#### NOTES:

1. Dimensions are in millimeters.  
Dimensions in ( ) for Reference Only.  
Allowable die thickness is 0.305mm. Maximum 0.012 inches.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ±0.05
4. Dimension b applies to the plated terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
5. The pin #1 identifier must exist on the top surface of the package by using indentation mark or other feature of package body.
6. Unilateral coplanarity zone applies to the exposed pad as well as the terminals.